

On June 19, 2018, the VLSI Technology and Circuits Committee met in Honolulu, Hawaii during the 2018 Symposium on VLSI Technology. This committee has face to face meetings twice a year during the IEDM and VLSI Symposium. This time EDS president, Fernando Guarin and EDTM 2019 Executive Committee, Aaron Thean were kindly invited the meeting.

The object of the VLSI Technology and Circuits Committee is to identify new and relevant areas of interest to the Electron Devices and Solid-State Circuits communities. Based on the nature of the areas, the committee recommends any or all of the following:

1. Initiate topical workshops of current interest (attached to existing conferences or incorporated in new ones)
2. Special issues for major publications (e.g., J-EDS)
3. Panel session topics for major conferences
4. Special sessions for major conferences

The following topics were discussed during the June meeting:

1. June BoG meeting feedback

EDS BoG meeting was held on June 2nd & 3rd at Cartagena, Columbia. The VLSI Technology and Circuits committee chair, Kazunari Ishimaru, attended the meeting and reported 2nd EDTM conference which was held on Mar. 12 to 16, 2018 at Kobe, Japan.

This time, one of the EDS Technical committee, Nanotechnology committee, helped to provide speakers and enabled featuring session “2D materials”. Asked other technical committee chairs to support future EDTM conference especially Packaging and Manufacturing area.

EDTM will have special issue on J-EDS also this year and reported current status. One of the BoG member commented that consider special issue not only J-EDS but also T-ED as a mini special issue. After discussion with EiC of T-ED, it was concluded that EDTM focus on J-EDS from the view point of publication cycle time and page charge advantage.

2. Status Updates

- 2-1: EDTM 2018 special issue on J-EDS

14 papers were selected by from Device (5), Process (4), Reliability/Modeling (3), and Materials (2) committees. Subcommittee chairs were assigned as guest editors. 3 papers are under review and remaining papers will come by the end of this month.

2-2: EDTM 2018 article for EDS news letter

This is behind the schedule. Proposal is combination with EDTM 2019 advertisement and submit to October issue.

2-3: VLSI Technology and Circuits committee home page

The committee home page needs update because some information are old. The chair is working on this and the new page will appear in July.

3. EDTM 2019 support

EDTM is the conference that EDS established and the VLSI Technology and Circuits committee fully supports this conference. This time, committee invited EDTM 2019 Executive committee, Aaron Thean, to share current status and the request from the committee.

The date (Mar. 12 to 15, 2019) and the venue (Marina Bay Sands Convention Center, Singapore) has already announced and CFP was distributed during the VLSI Symposium. What has changed from the last year was split of device committee (Group IV and non IV). The Committee organization and members were already fixed. Now the committee members start to collect input for Plenary, Invited, Tutorial, and Short Course speakers. Both Manufacturing and Packaging committee struggled to have papers last time. Those areas we should focus on especially for Singapore. The VLSI Technology and Circuits committee support to have papers by advertising other EDS Technical Committees.

The RF and 5G are the area we should also focus on and need to highlight for CFP.

4. How to keep EDTM healthy

The EDTM is newborn conference and need some system people recognize and draw submission / attendance.

EDS Japan chapter organizes IEDM report every February (after the IEDM conference, combined with Chapter general meeting). Executive committee reports summary of the conference and each subcommittee member reports highlights of the session. It is good EDTM also follow this system. Pick up several papers and give their presentation at local language will also help EDS members to know the EDTM conference.

This enables good visibility of EDTM to local EDS chapter. Combine with Distinguished Lecture will make more attractive this event.

Nominate active EDTM committee members to EDS Technical Committee member (not only our committee but also other committee) to support future EDTM conference from various technical scopes.

Invite EDTM Excom(past/future GC, TPC) to VLSI Technology and Circuits committee may also help to keep EDTM culture.

5. Others

Continuities are very important. Currently there are no common data base to keep past meeting minutes and materials. It is better EDS provide some online storage space for this purpose. Also WebEX meeting set up support for our future meeting is needed. Chiar will discuss with EDS office about these requests.

The next face-to-face meeting is during the IEDM conference. The date and time will be announced around October.

Please contact Kazunari Ishimaru (kazu.ishimaru@toshiba.co.jp) committee chair, for further information.

Kazu Ishimaru
EDS VLSI Technology and Circuits Committee Chair
Toshiba Memory Corporation

Attendees (attached picture): Sitting from left to right
Aaron Thean, Shu Ikeda, Hitoshi Wakabayashi, Kazu Ishimaru, Fernando Guarin, Pei-Wen Li

